## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Mizuki NAGAI et al.

Serial No. 10/664,078

Filed September 17, 2003

COPPER-PLATING LIQUID, PLATING METHOD AND PLATING APPARATUS

Confirmation No. 5067

Docket No. 2003 1338

Group Art Unit 1753

Examiner Edna Wong

Mail Stop: Amendment

## PETITION FOR EXTENSION OF TIME

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Petition hereby is made for a three month extension of time to respond to the communication of January 11, 2005.

The fee of \$1,020.00 is

- (X) submitted herewith.
- () to be charged to Deposit Account No. 23-0975. A duplicate copy of this Petition is enclosed.
- () Small entity status of this application is established by a Small Entity Status Assertion which

By\_

- () is enclosed.
- () has been previously submitted.

07/12/2005 HALI11 00000100 10664078

Respectfully submitted,

01 FC:1253

1020.00 OF

Mizuki NAGAI et al.

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

Matthew M. Jacob Registration No.25,154

Registration No.25,154 Attorney for Applicants

MJ/kes

Washington, D.C. 20006-1021 Telephone (202) 721-8200 Facsimile (202) 721-8250 July 8, 2005